

IN THE CLAIMS

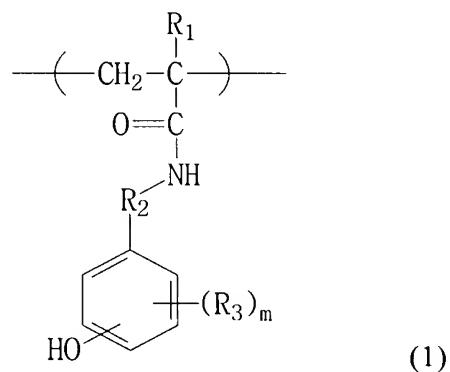
The status of each claim in the present application is listed below.

Claims 1-22: (Canceled).

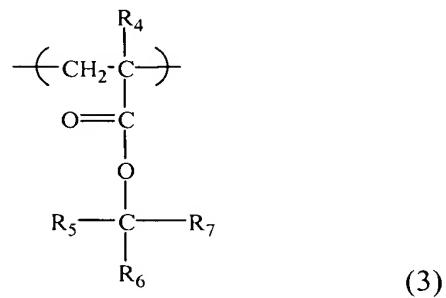
23. (New) A positive radiation-sensitive resin composition, comprising:

(A) a polymer containing structural units represented by formula (1), formula (3),

and structural units obtained from p-isopropenylphenol,



(1)



(3)

wherein

R<sub>1</sub> is a hydrogen atom or a methyl group,

R<sub>2</sub> is -(CH<sub>2</sub>)<sub>n</sub>-,

n is an integer of 0 to 3, R<sub>3</sub> is an alkyl group of 1 to 4 carbon atoms,

m is an integer of 0 to 4,

R<sub>4</sub> is a hydrogen atom or a methyl group,

R<sub>5</sub> to R<sub>7</sub> are each an alkyl group of 1 to 4 carbon atoms, an alicyclic hydrocarbon group of 4 to 20 carbon atoms, an aromatic group or a substituted hydrocarbon group, wherein at least one hydrogen atom in any one of these hydrocarbon groups is replaced with a polar group other than a hydrocarbon group, wherein R<sub>5</sub> to R<sub>7</sub> may be the same or different, and when any two of R<sub>5</sub> to R<sub>7</sub> are alkyl groups or substituted alkyl groups, their alkyl chains may be bonded to each other to form an alicyclic hydrocarbon group of 4 to 20 carbon atoms or a substituted alicyclic hydrocarbon group;

- (B) a component which generates an acid by irradiation with radiation; and
- (C) an organic solvent.

24. (New) The positive radiation-sensitive resin composition as claimed in claim 23, which is a composition for producing a plated shaped article.

25. (New) The positive radiation-sensitive resin composition as claimed in claim 24, wherein the plated shaped article is a bump.

26. (New) The positive radiation-sensitive resin composition as claimed in claim 23, wherein (B) is contained in an amount of 0.1 to 20 parts by weight based on 100 parts by weight of (A), and (C) is contained in an amount of 20 to 80 parts by weight based on the total weight 100 parts by weight of the positive radiation-sensitive resin composition.

27. (New) The positive radiation-sensitive resin composition as claimed in claim 23, which further comprises an alkali-soluble resin other than the polymer (A).

28. (New) The positive radiation-sensitive resin composition as claimed in claim 23, which further comprises an acid diffusion controller.

29. (New) The positive radiation-sensitive resin composition as claimed in claim 23, wherein the component (B) is at least one compound selected from the group consisting of 4-t-butylphenyl-diphenylsulfonium trifluoromethanesulfonate, 4-t-butylphenyl-diphenylsulfonium perfluoro-n-octanesulfonate, 4-t-butylphenyl-diphenylsulfonium pyrenesulfonate and 4,7-di-n-butoxynaphthyltetrahydrothiophenium trifluoromethanesulfonate.

30. (New) A transfer film having a resin film composed of the positive radiation-sensitive resin composition of claim 23 on a support film.

31. (New) The transfer film as claimed in claim 30, wherein the resin film has a film thickness of 20 to 100  $\mu\text{m}$ .

32. (New) A process for producing a plated shaped article, comprising:

- (1) forming a resin film composed of the positive radiation-sensitive resin composition of claim 23 on a wafer having a barrier metal layer,
- (2) exposing the resin film and then developing the resin film to form a pattern,
- (3) depositing an electrode material by electroplating using the pattern as a mold, and
- (4) stripping the remaining resin film and then removing the barrier metal by etching.